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Abstract of the Disclosure

HANDLER SYSTEM FOR CUTTING A SEMICONDUCTOR PACKAGE DEVICE

A handler system is provided with an on-loader unit for loading at least one of strips deposited in a cassette, a drawer unit for holding the strip from the on-loader unit at a drawer picker, a strip transferring unit for fixing in a suction manner after the holding its picker head and for transferring the strip to a cutting device, cut it into a plurality of individual package devices, a package cleaning unit for cleaning the individual package devices using a brush and an air nozzle after to fixing and retaining the individual package devices thereon by using a suction vacuum force, a package drying unit for drying the individual package devices after the cleaning, a package deposit unit for moving and depositing after drying, a package pick-up unit for retaining and for arranging the individual package devices for a quality inspection, the package pick-up unit mounted on one side of the package deposit unit, a visual inspection means for inspecting the quality of the individual package devices being, and a package tray deposit unit for retaining the individual package devices C thereon by using the suction vacuum force to seat the individual package devices on the package deposit unit, the package tray deposit unit for transferring the tray on which the individual package devices classified based on the inspection result are contained.

Fig. 1a

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